

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00848	1.2	0.1284
	Doped silicon	Silicon (Si)	7440-21-3	0.6982	98.8	10.5716
Subtotal				0.70668	100	10.7
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03848	10.0	0.58271
	Silver alloy	Silver (Ag)	7440-22-4	0.0077	2.0	0.11654
	Lead alloy	Lead (Pb)	7439-92-1	0.33866	88.0	5.12782
Subtotal				0.38484	100	5.82707
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.27793	100.0	4.20829
	Subtotal				0.27793	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0097	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00647	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.0097	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03558	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.28644	99.81	488.8594
Subtotal				32.34789	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34125	100.0	5.167
	Subtotal				0.34125	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.27531	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.41253	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46159	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19782	0.3	2.99532
	Polymer	Epoxy resin system		6.59414	10.0	99.844
Subtotal				65.94139	100	998.44
Total				99.99998	100	1514.13237

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.